



ICMDA 2026

Tohoku University,
Sendai, Japan
April 17-20, 2026

Call for Paper

Topics of interest for submission include, but are not limited to:

Materials Properties, Measuring Methods and Applications:

- Ductility
- Crack Resistance
- Fatigue
- Creep-resistance

Materials Science and Materials

Processing Technology:

- Composite
- Micro/Nano materials
- Iron & Steel
- Ceramics

Materials Analyses and Modeling:

- Electron Microscopy
- Image Analysis
- X-ray Phase Analysis
- Computational Material Science
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Contact US

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Proceedings

Accepted and registered papers with presentation will be published in journals of [Scientific.Net](#) collection. Papers will be sent for indexing by **Scopus**, Inspec, Chemical Abstracts Service, Google Scholar etc.

Conference Committees

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Speakers



Prof. Takaaki Tomai
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Prof. Yimin Chao
Foshan Xianhu
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Prof. Lung-Hao Hu,
National Sun Yat-sen
University (NSYSU),
Taiwan



Dr. Adrian Radoń, Center of Functional
Materials, Łukasiewicz Research
Network – Institute of Non-Ferrous
Metals, Poland

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Important Date

Submission Deadline: **Mar. 5, 2026**

Notification Deadline: **Mar. 15, 2026**

Registration Deadline: **Mar. 20, 2026**